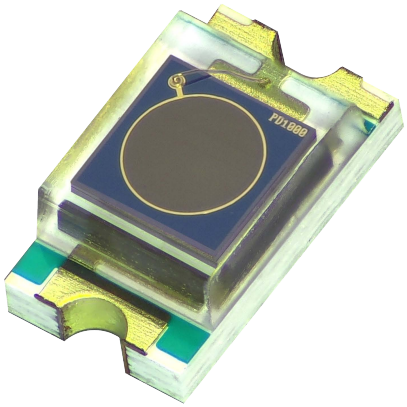
产品介绍 / Product Introduction:

NDT7010是一个灵敏度在近红外范围的InGaAs PD
NDT7010 is an InGaAs PD with sensitivity in the near infrared range

特点 / Features:

·高速
High speed

·高响应度
High responsivity

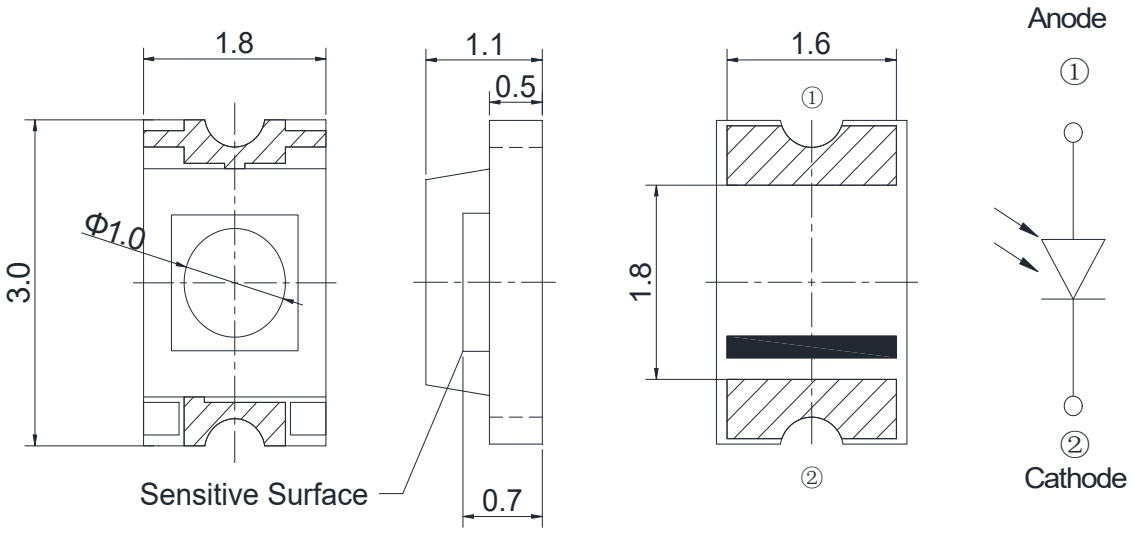


用途 / Application:

·光度监视
Light monitor

·光纤仪器
Fiber-optic instruments

制品尺寸图 / Device Dimensions (mm):



Tolerances are ±0.1mm

极限值 / Maximum Ratings

(Ta= 25℃)

项目 Item	符号 Symbol	额定值 Rating	单位 Unit
反向电压 Reverse Voltage	V_{RMax}	20	V
工作温度 Operating temp.	Topr.	-20～80	℃
存储温度 Storage temp.	Tstg.	-20～100	℃
焊接温度*1 Soldering temp.	Tsol.	260	℃

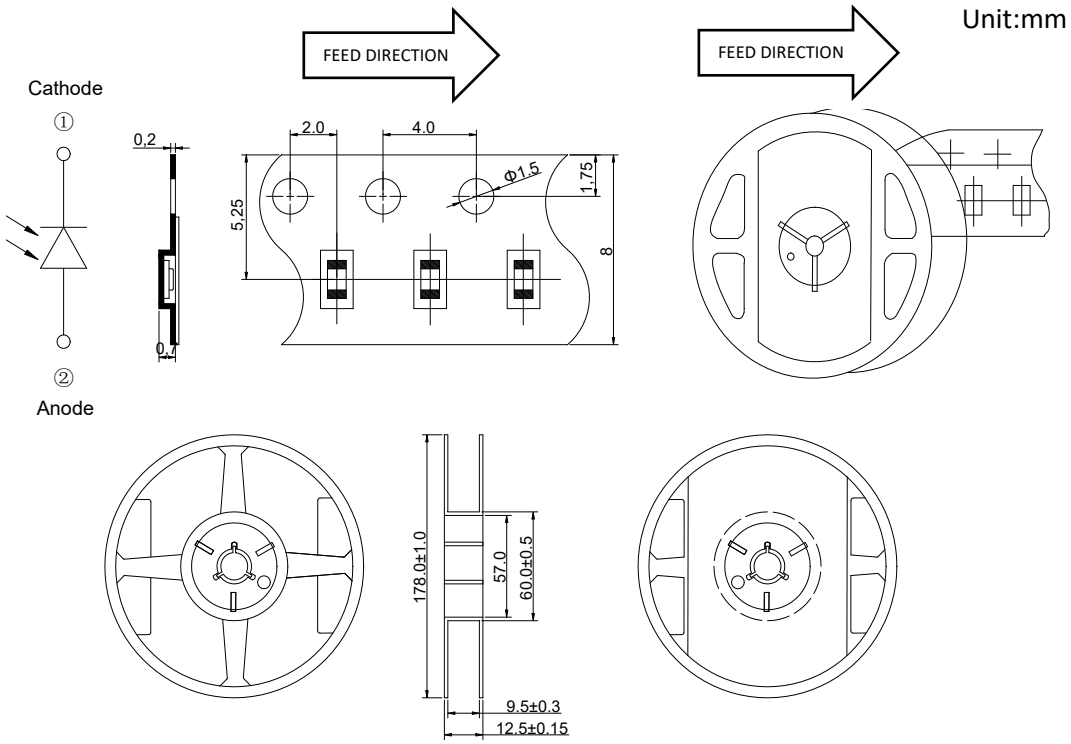
Note: 1. 在焊盘处不超过5秒
For MAX. 5 seconds at the position of pad.

光电特性 / Electro-optical Characteristics

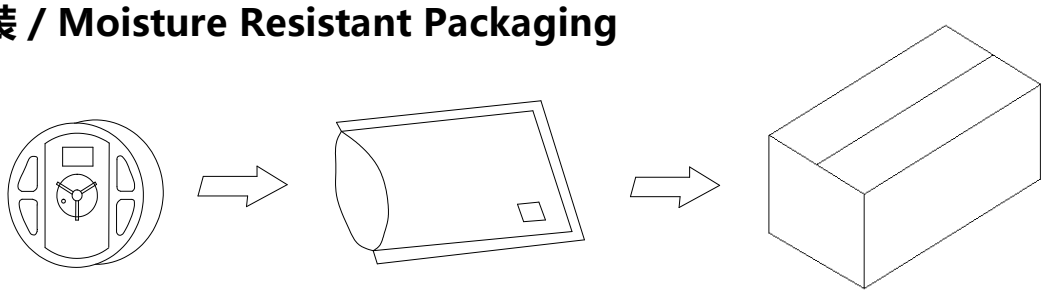
(Ta= 25℃)

项目 Items	符号 Symbol	条件 Condition	最小 Min.	典型 Typ.	最大 Max.	单位 Unit
响应度 Responsivity	R	λ=1310nm	0.75	0.9	-	A/W
		λ=1550nm	-	0.95	-	
暗电流 Dark Current	I_D	V_R=5V	-	1.5	10	nA
光谱响应度 Spectral Sensitivity	λ	-	900	-	1650	nm
带宽 Bandwidth	Bw	V=0V, RL=50Ω, -3dB	-	40	-	MHz
电容 Capacitance	Ct	V_R=5V，f=1MHz	-	50	80	pF

卷轴尺寸 / Carrier Tape Dimensions



防潮包装 / Moisture Resistant Packaging



1 Reel(1,000pcs)　　1bag(1Reel)　　1box(5 Bag)

注意：
Note:

1.所有尺寸除非另有说明，否则单位均为毫米，公差为±0.2毫米
All Dimensions are in millimeters, Tolerance is ±0.2mm unless otherwise noted .

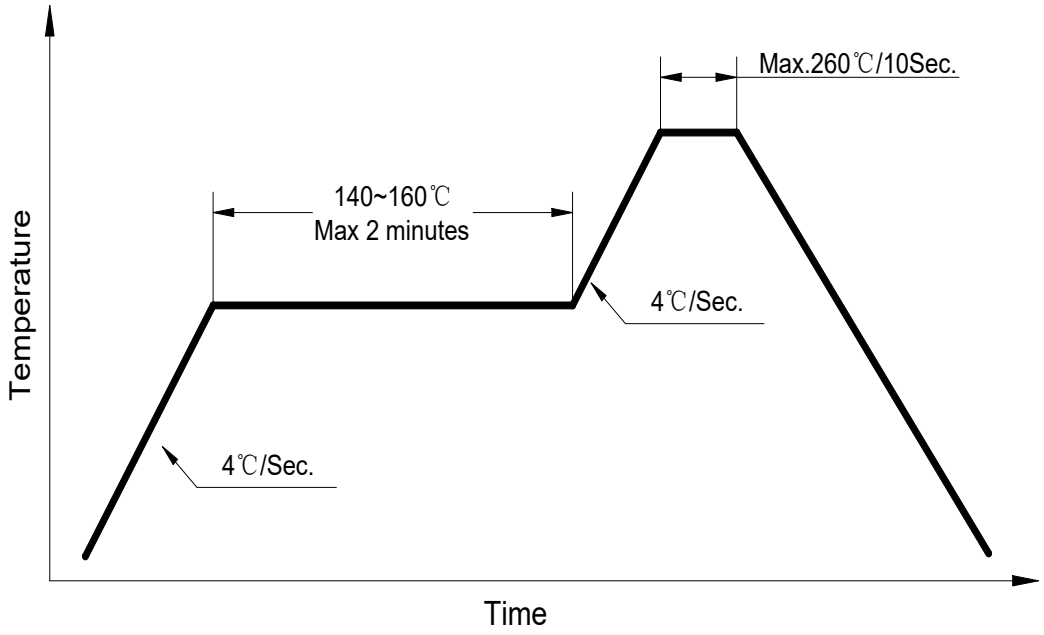
2.规格如有变更，恕不另行通知
Specifications are subject to change without notice.

3.1,000pcs/袋， 5,000pcs/箱
1Bag:1,000pcs， 1Box:5,000pcs

4.采用真空、防潮、防静电袋包装
Packing with vacuum moisture-proof and anti-static bags.

5.每个袋内都配有干燥剂
Desiccant are put into the each bag.

回流焊参考曲线 / Reflow Soldering Temp/Time Profile



注意 / Caution

1.开启包装前，请按如下条件保存：

Before the bag is opened, please keep the following storage condition:

温度 T=5℃～30℃，湿度 RH<60%，时间 t<12个月。

Temperature: 5℃-30 ℃,Humidity:RH 60% Max ,Time:12 Months.

2.开启包装后，如果器件要进行红外、气相回流焊或其它相似工艺焊接，请按如下方式保存：

After this bag is opened , The device that will be applied to infrared reflow,vapor-phase reflow,or equivalent soldering process must be :

a)保存湿度 RH<20%;

Stored at less than 20% RH;

b)在168小时内可以完成焊接时，保存条件：温度 T<30℃，湿度 RH<60%；

Mounted within 168hours：Temperature: 30℃ Max, Humidity:RH 60% Max;

c）在包装开启时，如果湿度指示卡显示超过30%，请烘烤后再进行回流焊接。

When opened the Bag,the value of Humidity card is exceed 30%,Baking is required before mounting.

3.如果没有满足上述条件，则再次焊接前需要进行烘烤。

If above conditions are not met , baking is required before mounting.

烘烤条件：t=12小时，T=60℃±3℃，RH<5%

Baking condition :12 hours at 60±3℃ and <5% RH.